

*ABSTRACT AMENDMENT*

Replace the Abstract with:

An assembly substrate, on which a plurality of semiconductor chips, each having a terminal receiving a burn-in test waveform, are arranged, is detachably attached to a burn-in test adapter. The burn-in test adapter has a wiring ~~arranged in such a manner that for~~, when ~~the an~~ assembly substrate is attached to the burn-in test adapter, ~~the wiring makes~~ making an electrical contact with the terminal of each of the semiconductor chips on the assembly substrate. Moreover, the burn-in test adapter has a burn-in test terminal that is electrically connected to the wiring and that receives the burn-in test waveform.